

CMS10N10Q8-HF

N-Channel
RoHS Device
Halogen Free

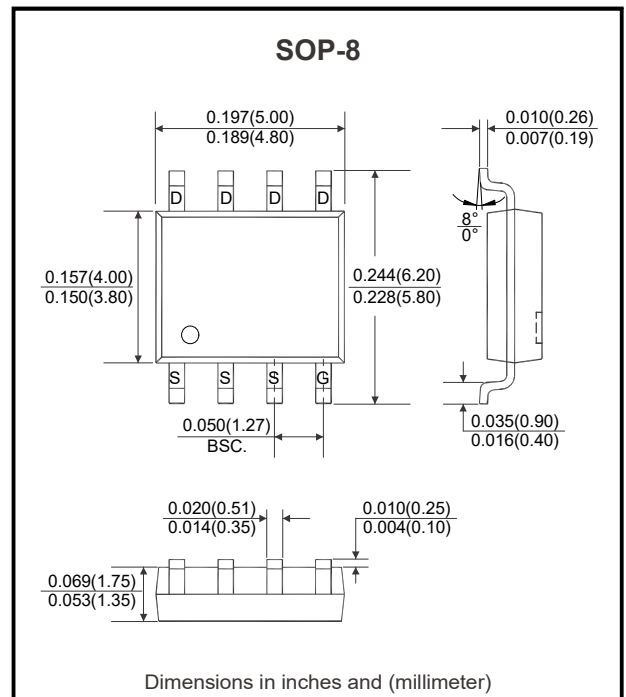


Features

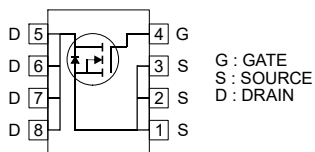
- Advanced high cell density Trench technology.
- Excellent CdV/dt effect decline.
- Green Device Available.
- Super Low Gate Charge.
- 100% EAS Guaranteed.

Description

The CMS10N10Q8 is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent $R_{DS(ON)}$ and gate charge for most of the synchronous buck converter applications. The CMS10N10Q8 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.



Circuit diagram



Maximum Ratings (at $T_C=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹	$I_D @ T_A=25^\circ\text{C}$	10	A
	$I_D @ T_A=70^\circ\text{C}$	8	A
Pulsed Drain Current ^{2,6}	I_{DM}	28	A
Single Pulse Avalanche Energy, $L=3\text{mH}^3$	EAS	63	mJ
Single Pulse Avalanche Current, $L=3\text{mH}^3$	I_{AS}	6.5	A
Total Power Dissipation ⁴	$P_D @ T_A=25^\circ\text{C}$	2.5	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	$-55 \sim +150$	$^\circ\text{C}$

Thermal Data

Parameter	Symbol	Conditions	Max. Value	Unit
Thermal Resistance Junction-ambient ¹	$R_{\theta JA}$	$t \leq 10\text{s}$	50	$^\circ\text{C/W}$

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Electrical Characteristics (at $T_C=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	BV_{DSS}	100	-	-	V	$V_{GS}=0, I_D=250\mu\text{A}$
Gate Threshold Voltage	$V_{GS(th)}$	1.2	1.8	2.5	V	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$
Gate-Source Leakage Current	I_{GSS}	-	-	± 100	nA	$V_{GS}=\pm 20\text{V}$
Drain-Source Leakage Current	I_{DSS}	-	-	1	μA	$V_{DS}=80\text{V}, V_{GS}=0$
Static Drain-Source On-Resistance ²	$R_{DS(on)}$	-	-	25.5	m Ω	$V_{GS}=10\text{V}, I_D=10\text{A}$
		-	-	28.5		$V_{GS}=4.5\text{V}, I_D=8\text{A}$
Total Gate Charge ²	Q_g	-	31	-	nC	$I_D=7\text{A}$ $V_{DS}=50\text{V}$ $V_{GS}=10\text{V}$
Gate-Source Charge	Q_{gs}	-	5.1	-		
Gate-Drain ("Miller") Charge	Q_{gd}	-	7.3	-		
Turn-on Delay Time ²	$T_{d(on)}$	-	11	-	ns	$V_{DS}=50\text{V}$ $I_D=7\text{A}$ $V_{GS}=10\text{V}$ $R_G=3\Omega$
Rise Time	T_r	-	42	-		
Turn-off Delay Time	$T_{d(off)}$	-	40	-		
Fall Time	T_f	-	19	-		
Input Capacitance	C_{iss}	-	1519	-	pF	$V_{GS}=0\text{V}$ $V_{DS}=30\text{V}$ $f=1.0\text{MHz}$
Output Capacitance	C_{oss}	-	132	-		
Reverse Transfer Capacitance	C_{rss}	-	66	-		

Guaranteed Avalanche Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Single Pulse Avalanche Energy ⁵	EAS	34.5	-	-	mJ	$V_{DD}=50\text{V}, L=3\text{mH}, I_{AS}=4.8\text{A}$

Source-Drain Diode

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Forward On Voltage ²	V_{SD}	-	0.78	1.3	V	$I_S=10\text{A}, V_{GS}=0\text{V}, T_J=25^{\circ}\text{C}$
Reverse Recovery Time	T_{rr}	-	32	-	ns	$I_F=10\text{A}, dI/dt=500\text{A}/\mu\text{s}, T_J=25^{\circ}\text{C}$
Reverse Recovery Charge	Q_{rr}	-	200	-	nC	$T_J=25^{\circ}\text{C}$

Notes: 1. Surface mounted on a 1 inch² FR-4 board with 20Z copper.

2. The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.

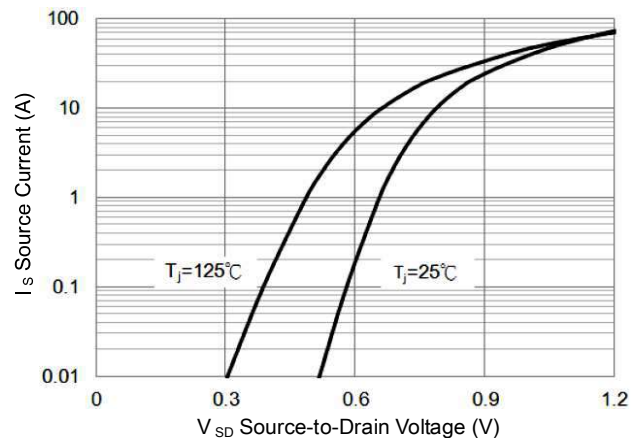
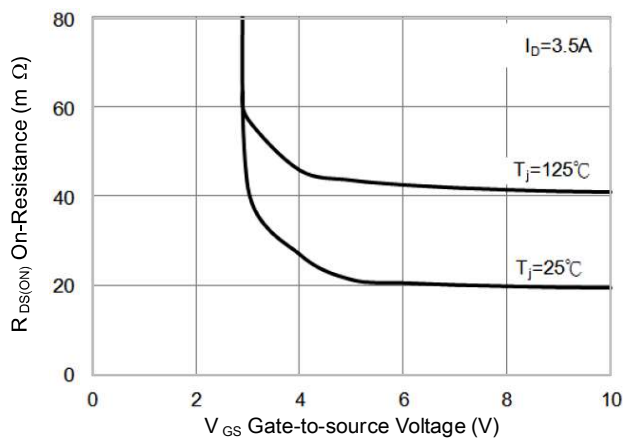
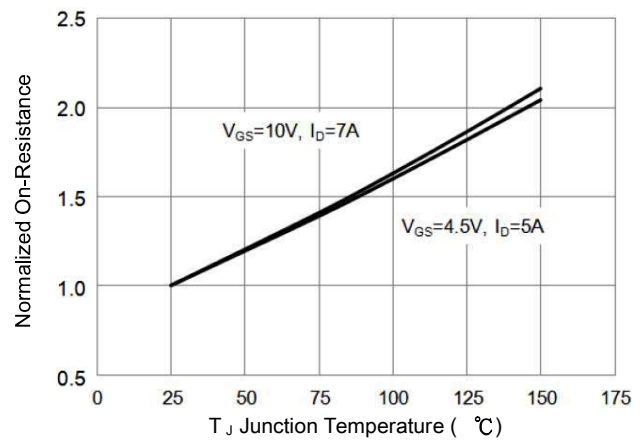
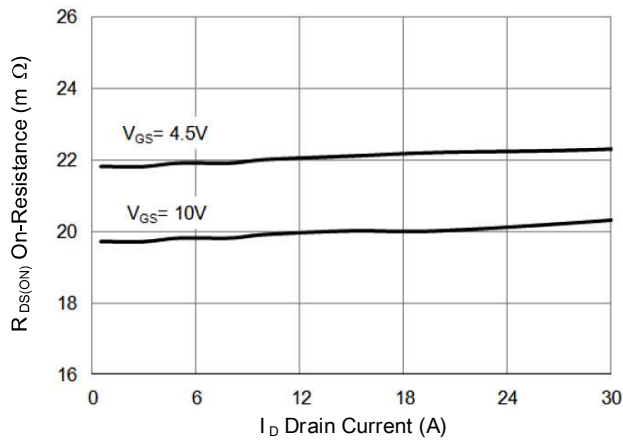
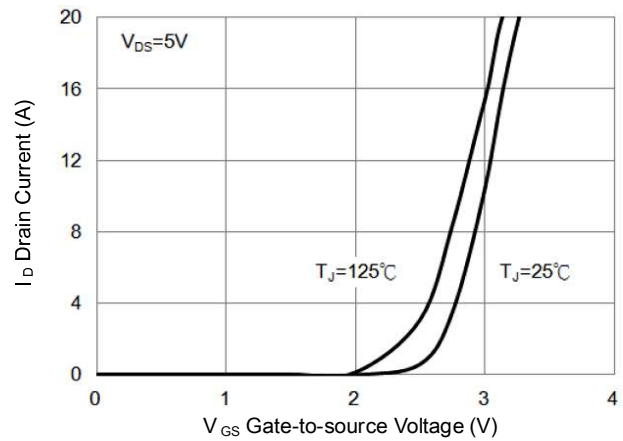
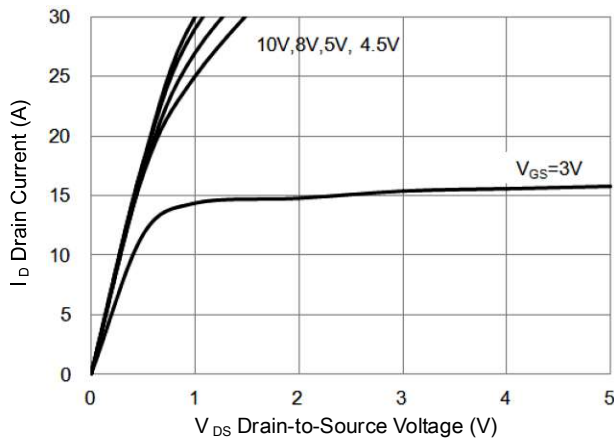
3. The EAS data shows Max. rating. The test condition is $V_{DD}=50\text{V}, V_{GS}=10\text{V}, L=3\text{mH}, I_{AS}=6.5\text{A}$.

4. The power dissipation is limited by 150°C junction temperature.

5. The Min. value is 100% EAS tested guarantee.

6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.

TYPICAL RATING AND CHARACTERISTIC CURVES



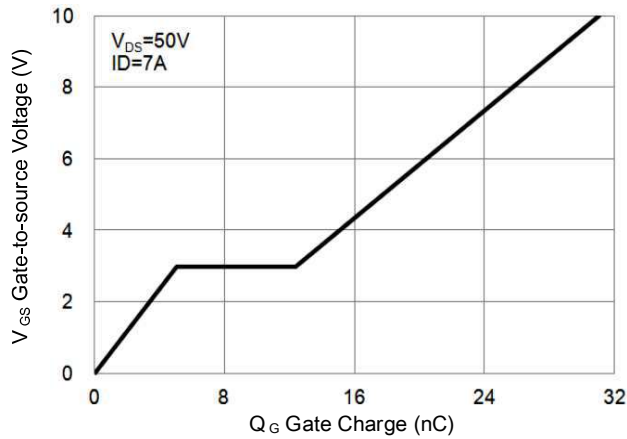


Fig.7 Gate Charge Characteristics

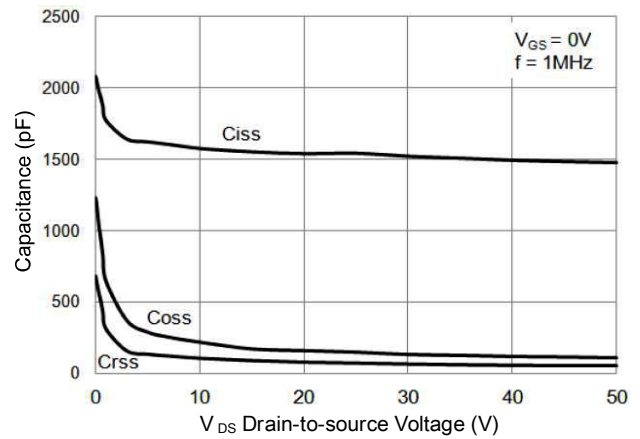


Fig.8 Capacitance Characteristics

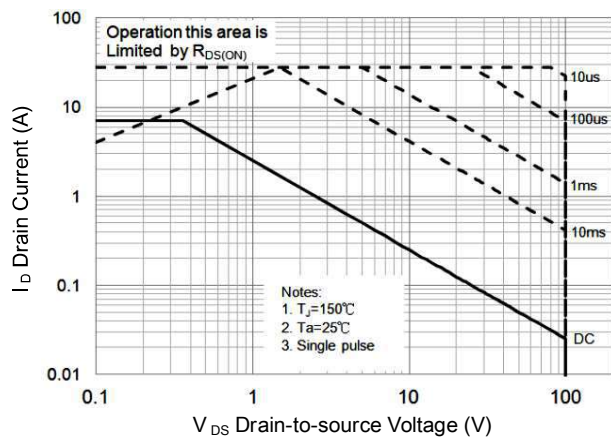


Fig.9 Safe Operating Area

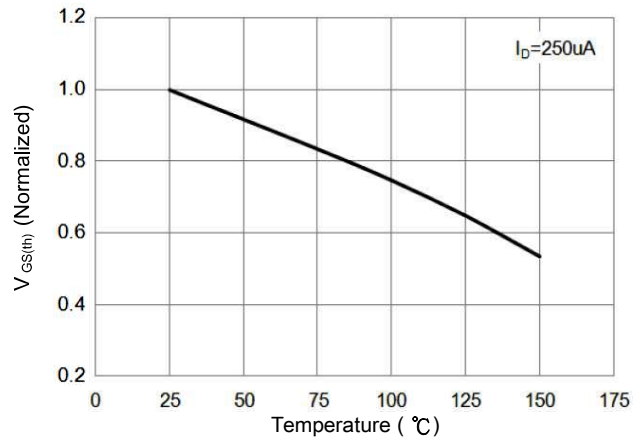


Fig.10 Normalized $V_{GS(th)}$ vs. Temperature

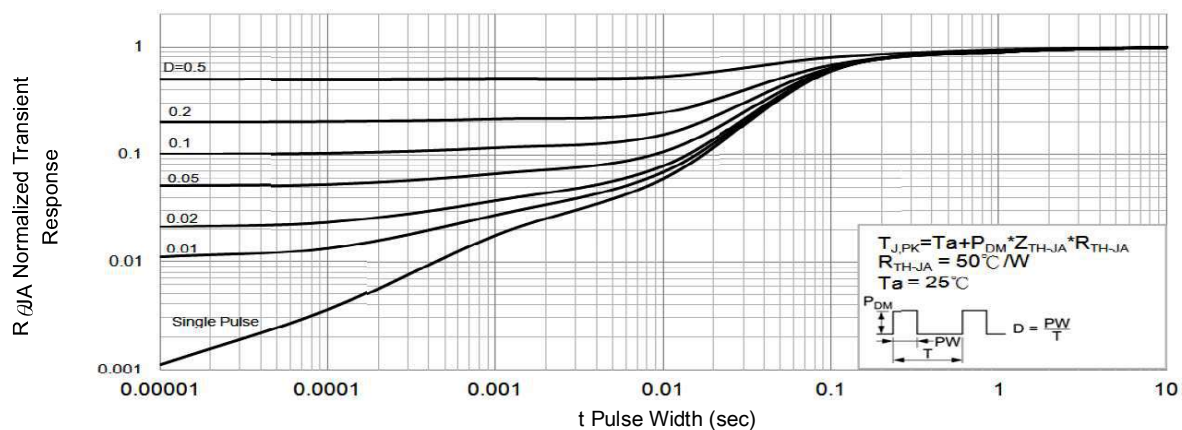
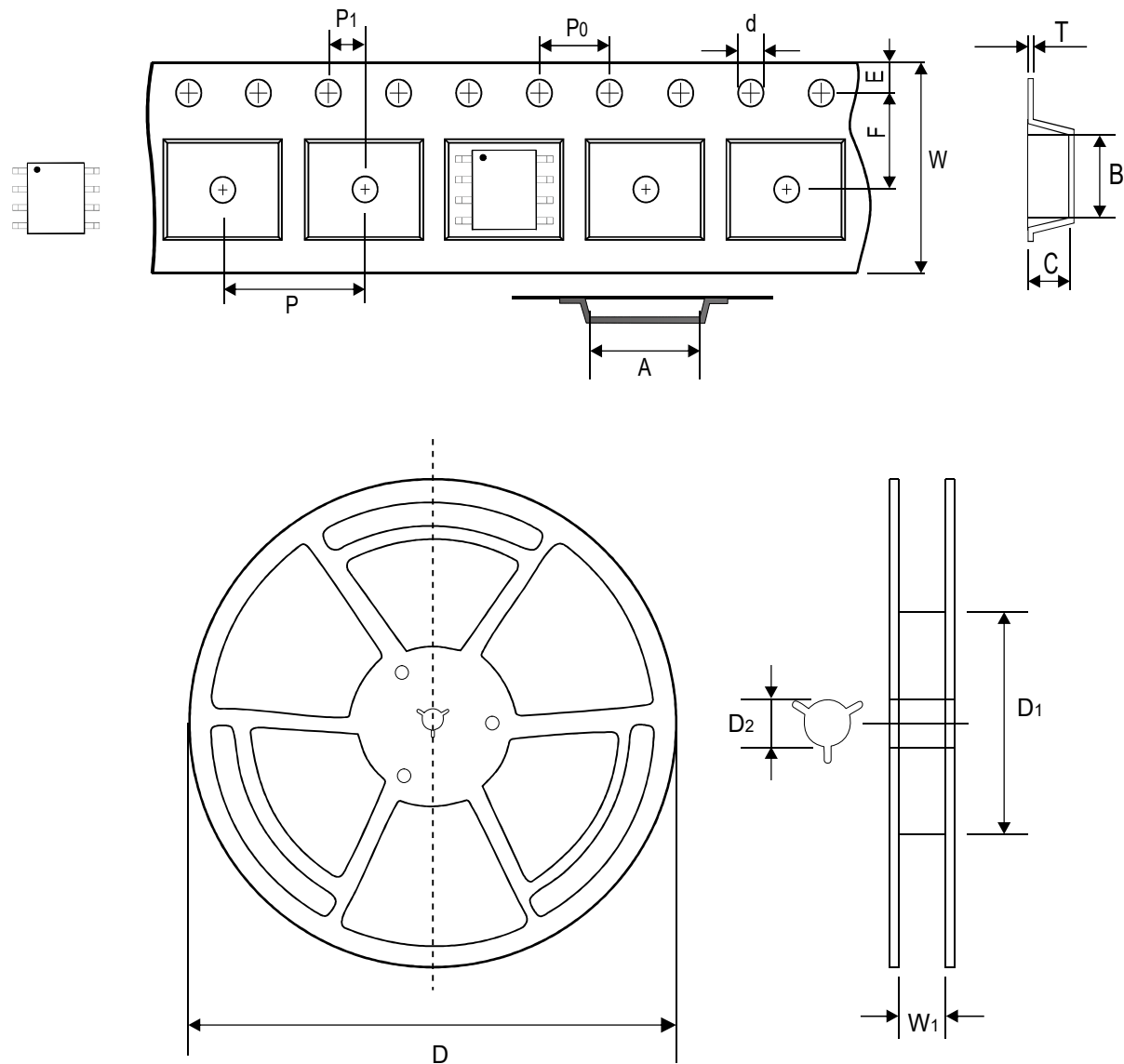


Fig.11 Normalized Maximum Transient Thermal Impedance

Reel Taping Specification



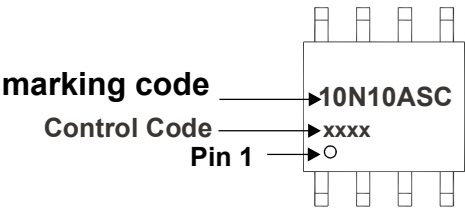
SOP-8	SYMBOL	A	B	C	d	D	D1	D2
	(mm)	6.40 ± 0.10	5.20 ± 0.10	2.10 ± 0.10	1.50 + 0.10 - 0.00	330.00 ± 1.00	100.00 ± 0.50	13.00 ± 0.20
	(inch)	0.252 ± 0.004	0.205 ± 0.004	0.083 ± 0.004	0.059 + 0.004 - 0.000	12.992 ± 0.039	3.937 ± 0.020	0.512 ± 0.008

SOP-8	SYMBOL	E	F	P	P0	P1	T	W	W1
	(mm)	1.75 ± 0.10	5.50 ± 0.05	8.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.05	0.25 ± 0.02	12.00 + 0.30 - 0.10	17.60 + 1.00 - 0.00
	(inch)	0.069 ± 0.004	0.217 ± 0.002	0.315 ± 0.004	0.157 ± 0.004	0.079 ± 0.002	0.010 ± 0.001	0.472 + 0.012 - 0.004	0.693 + 0.039 - 0.000

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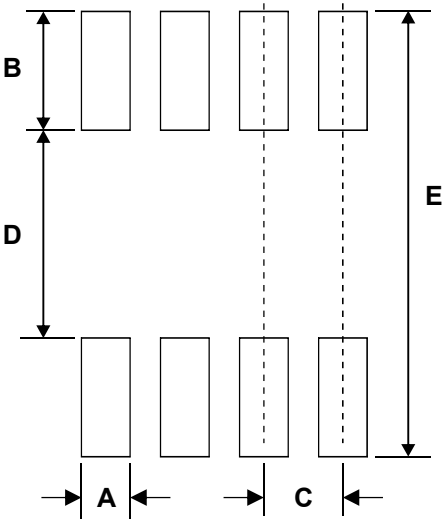
Marking Code

Part Number	Marking Code
CMS10N10Q8-HF	10N10ASC



Suggested PAD Layout

SIZE	SOP-8	
	(mm)	(inch)
A	0.60	0.024
B	1.52	0.060
C	1.27	0.050
D	4.00	0.157
E	7.00	0.275



Standard Packaging

Case Type	REEL PACK	
	REEL (pcs)	Reel Size (inch)
SOP-8	3,000	13